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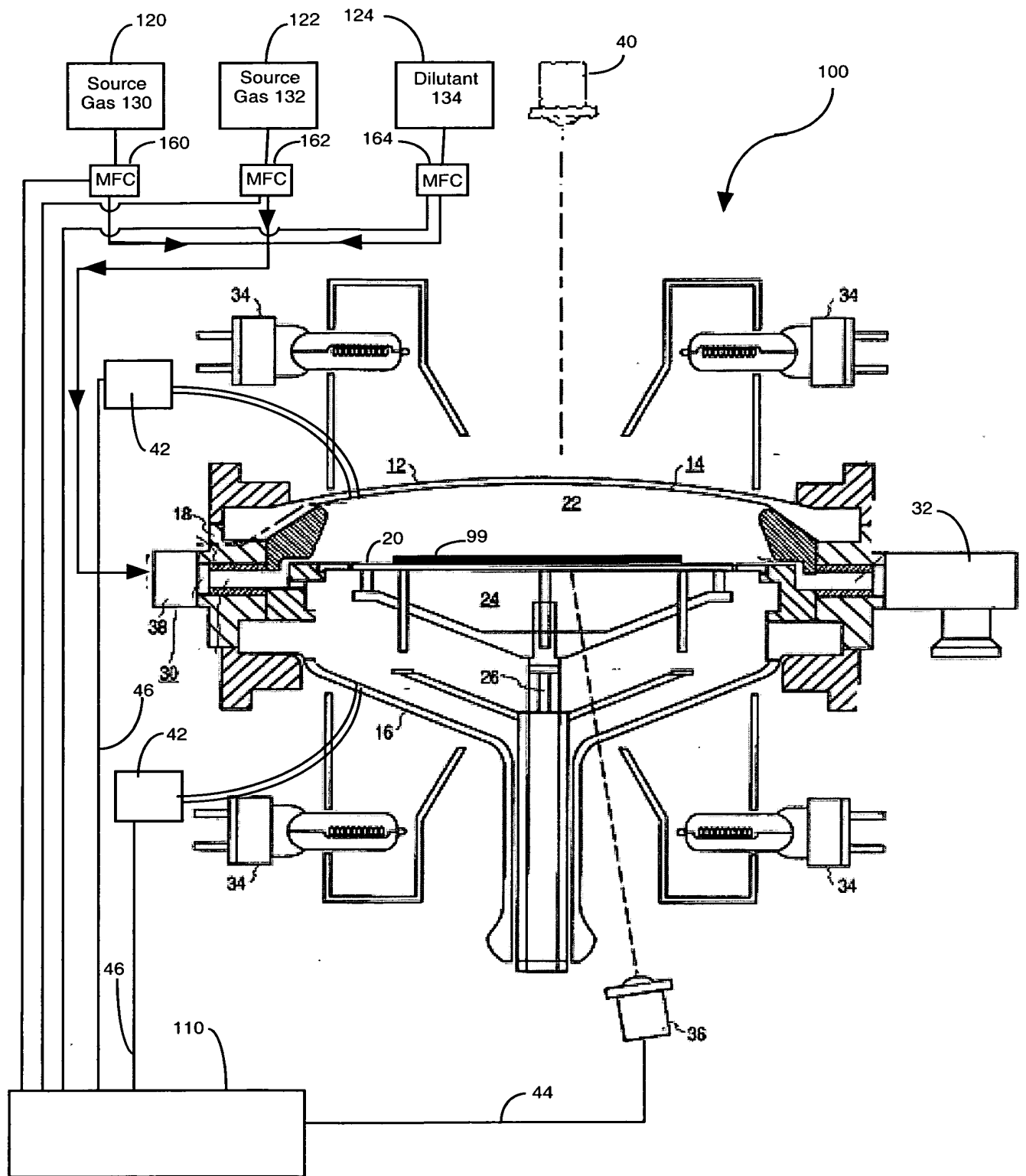


Figure 1

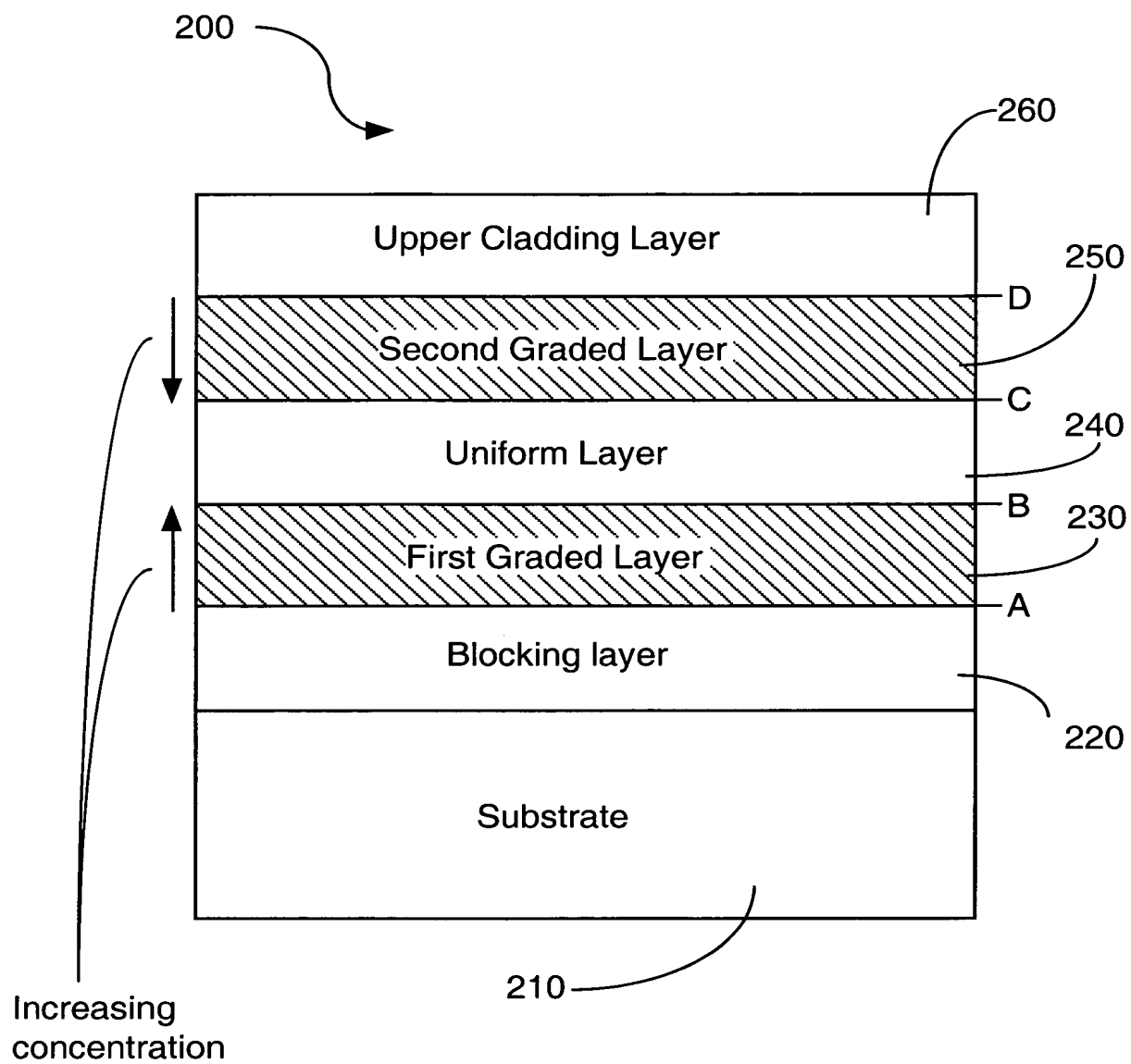


Figure 2

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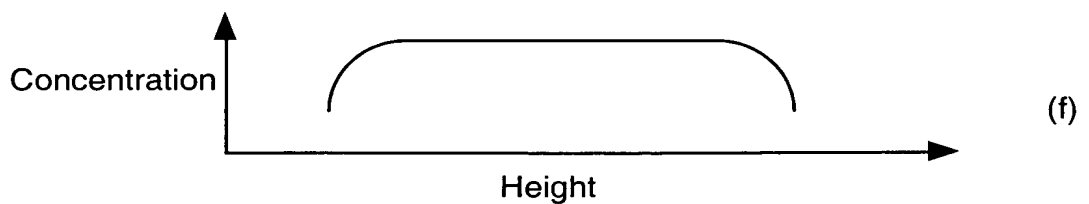
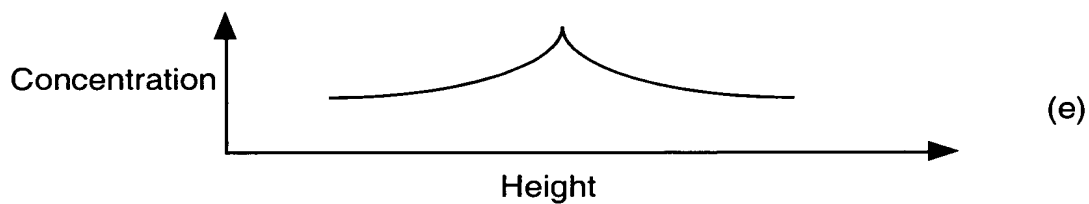
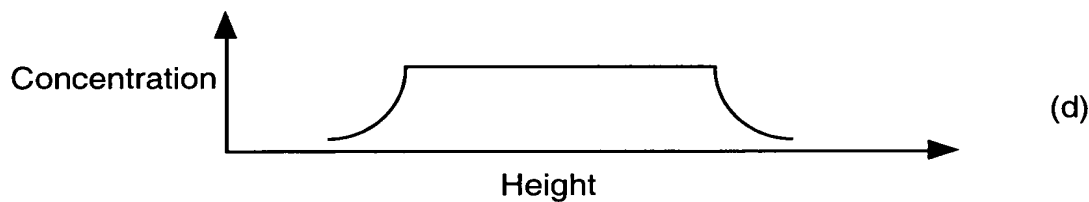
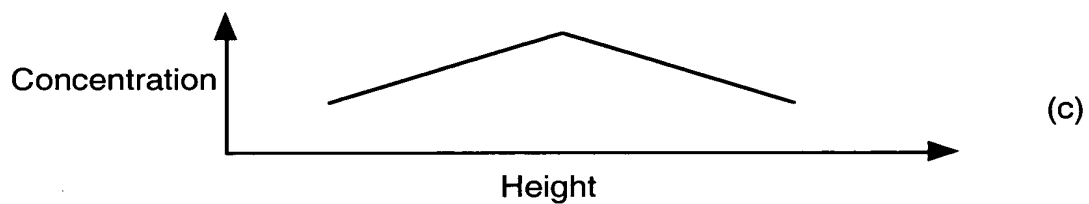
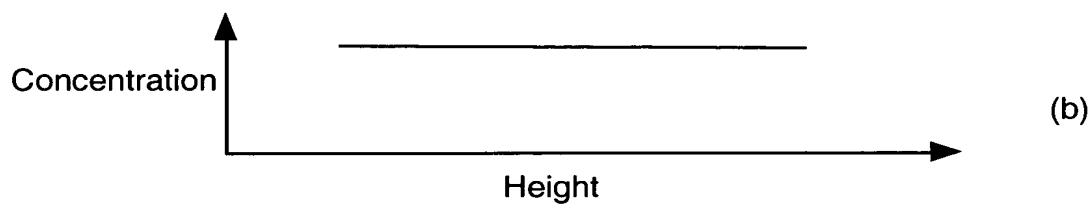
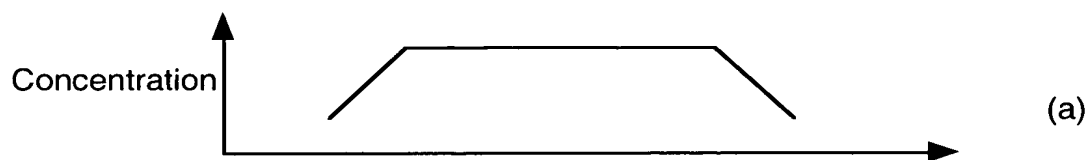
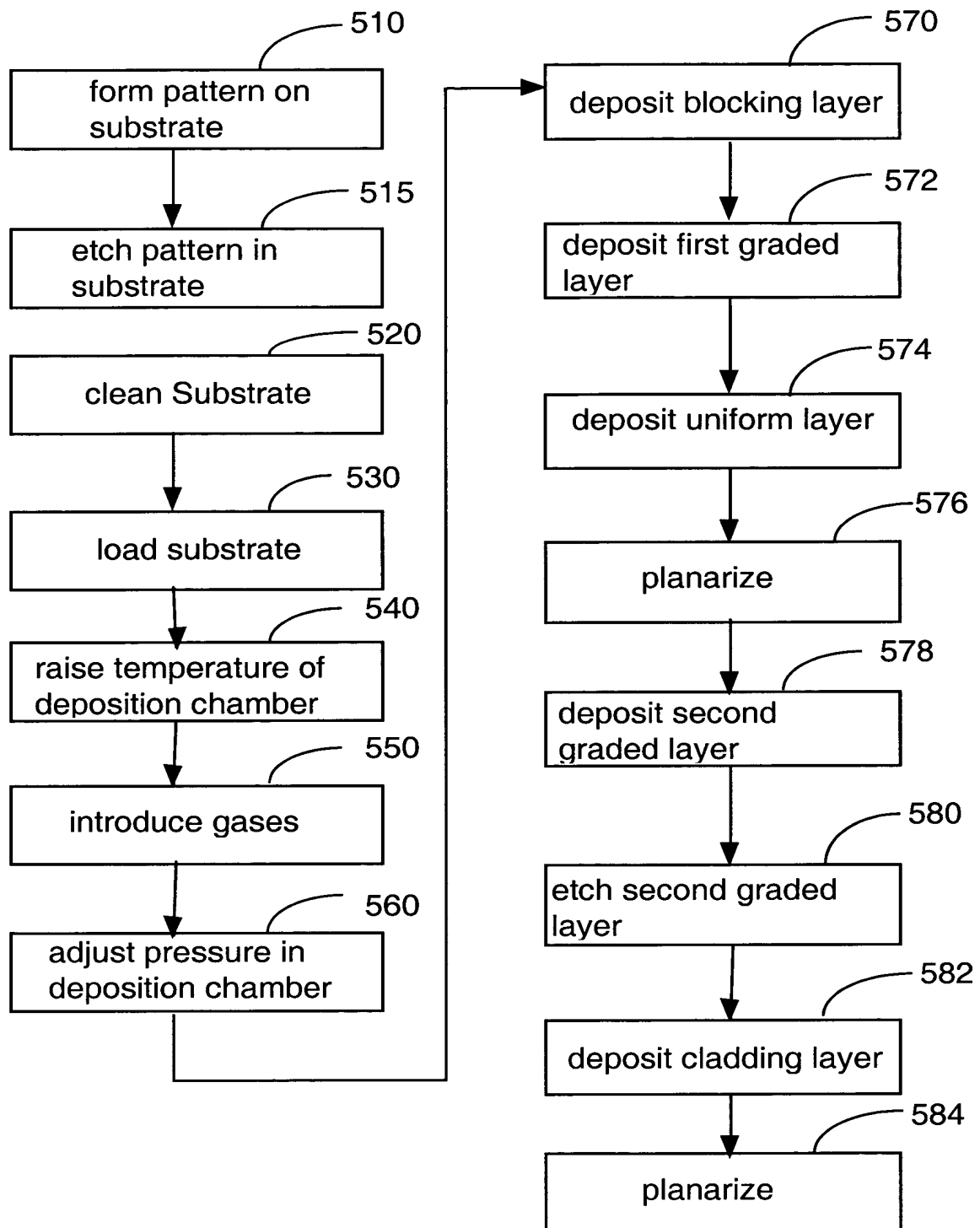
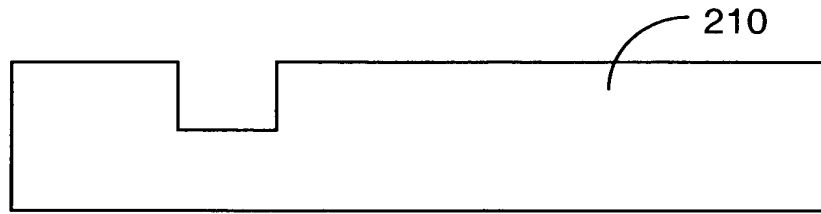


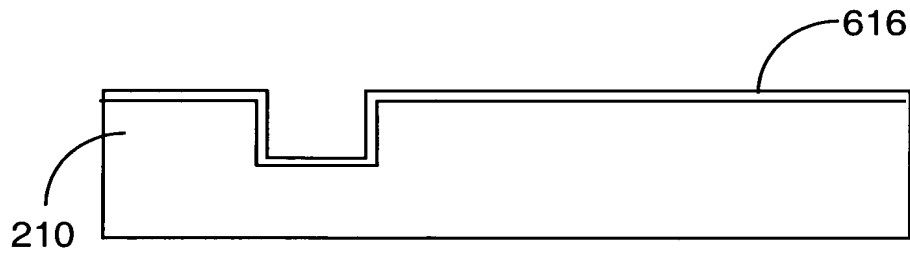
Figure 3

**Figure 4**

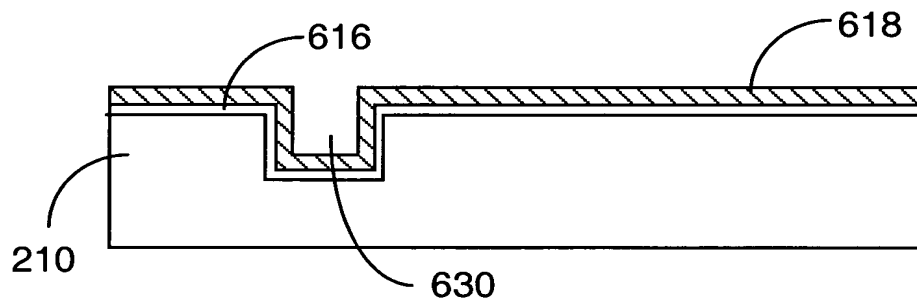
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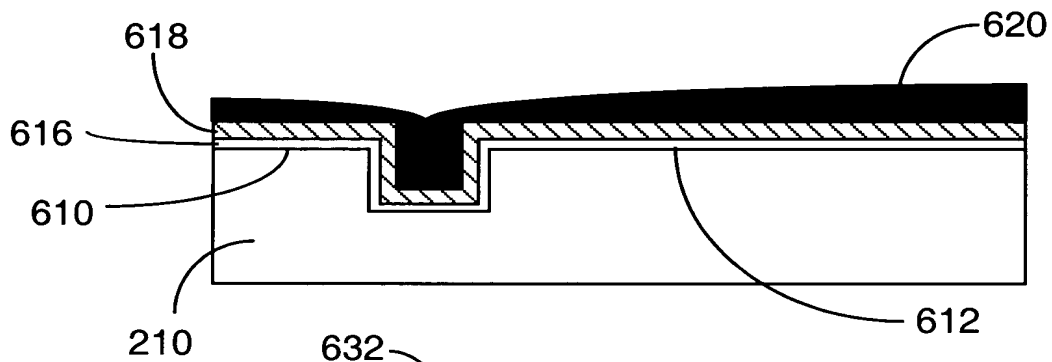
(a)



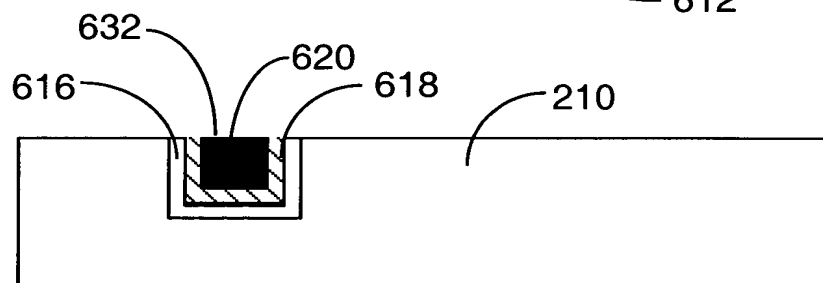
(b)



(c)



(d)



(e)

Figure 5

FIG. 5 is a schematic diagram of a device 210 in four cross-sectional views (f), (g), (h), and (i) showing different stages of a manufacturing process. The device 210 includes a substrate 616 and a central region 620. In (f), a layer 618 is formed on top of 620, and a layer 622 is formed on top of 618. In (g), the layer 622 is patterned into a grid-like structure. In (h), a layer 624 is formed on top of the device 210. In (i), the layer 624 is patterned into a grid-like structure.

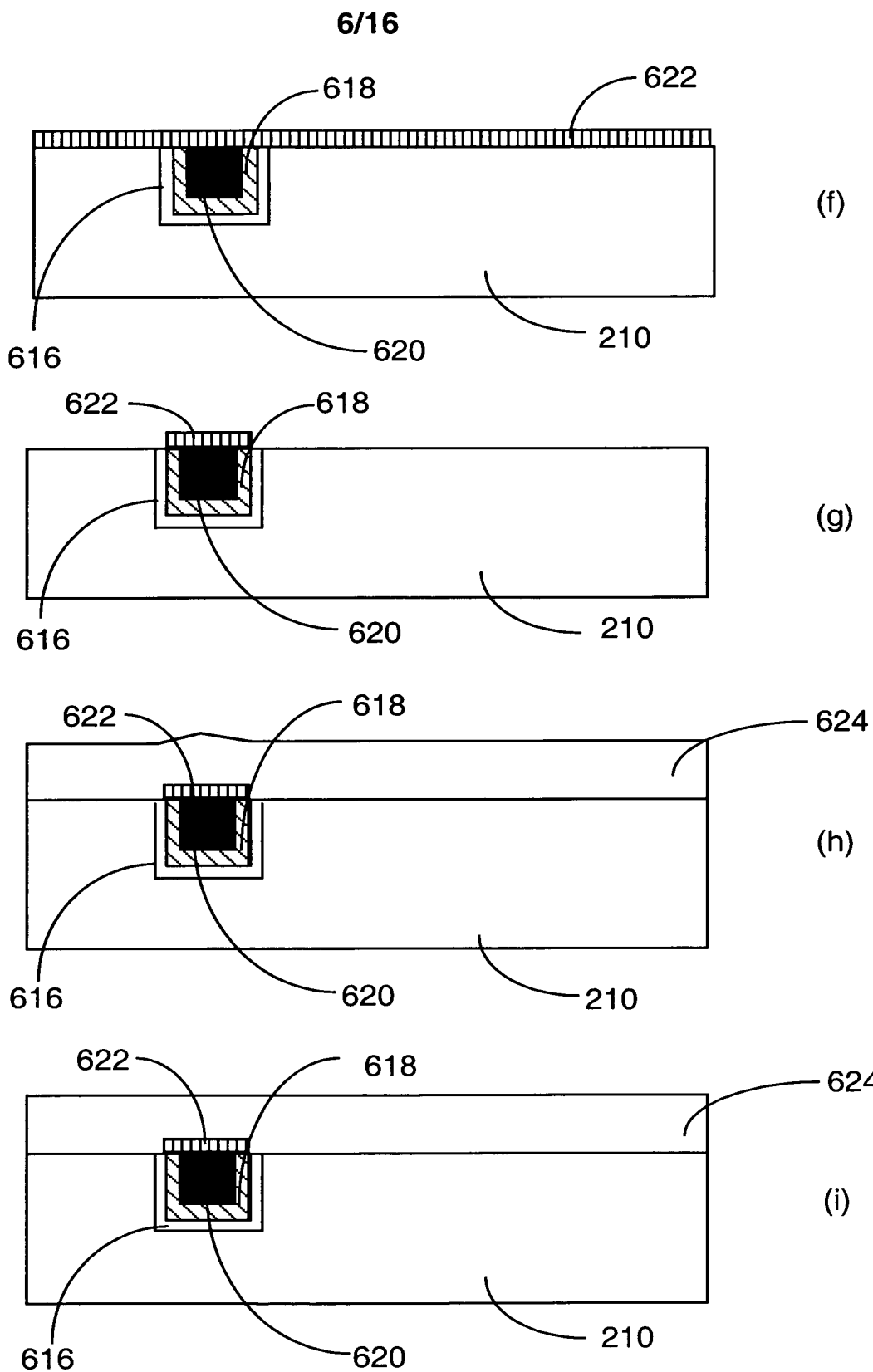
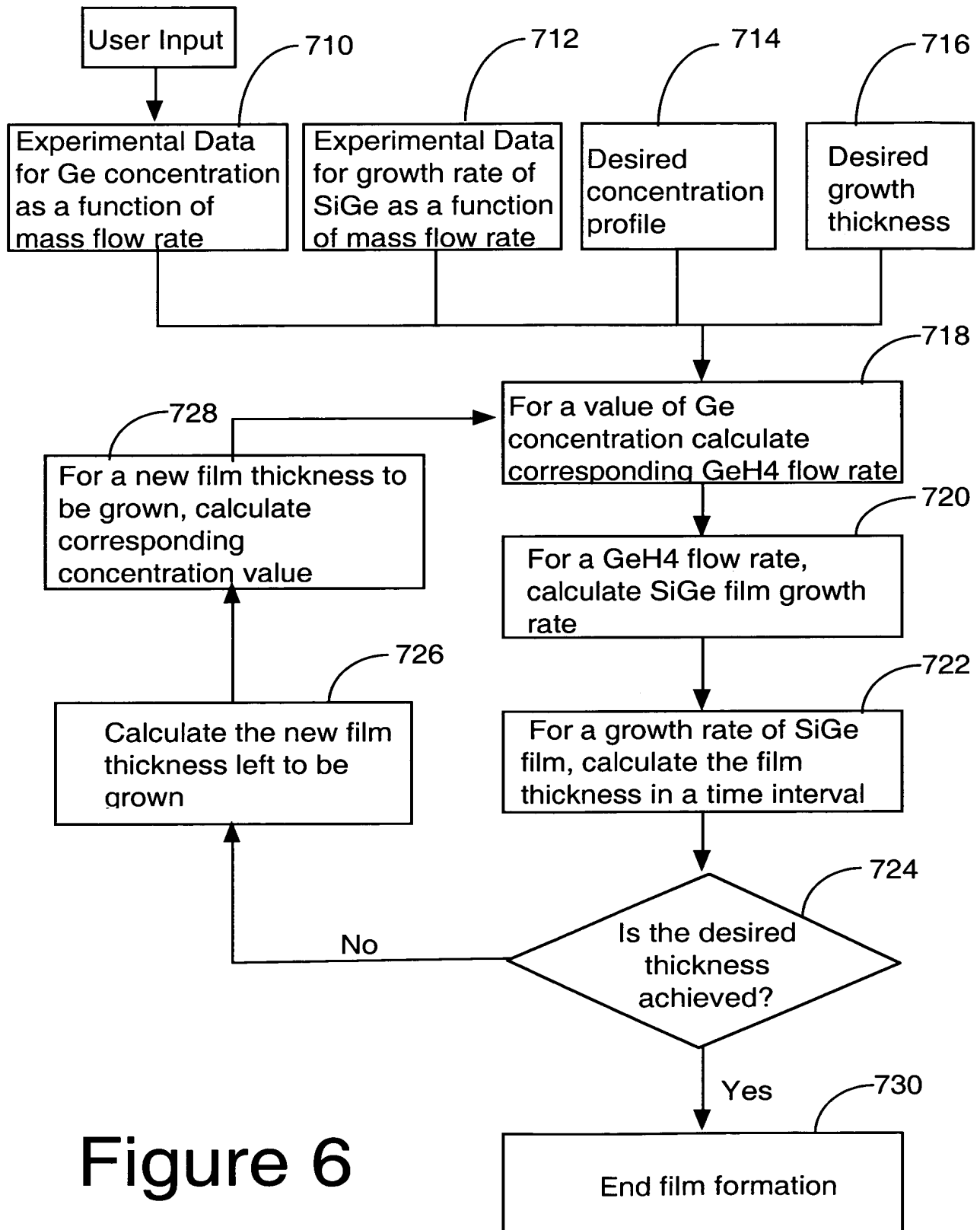
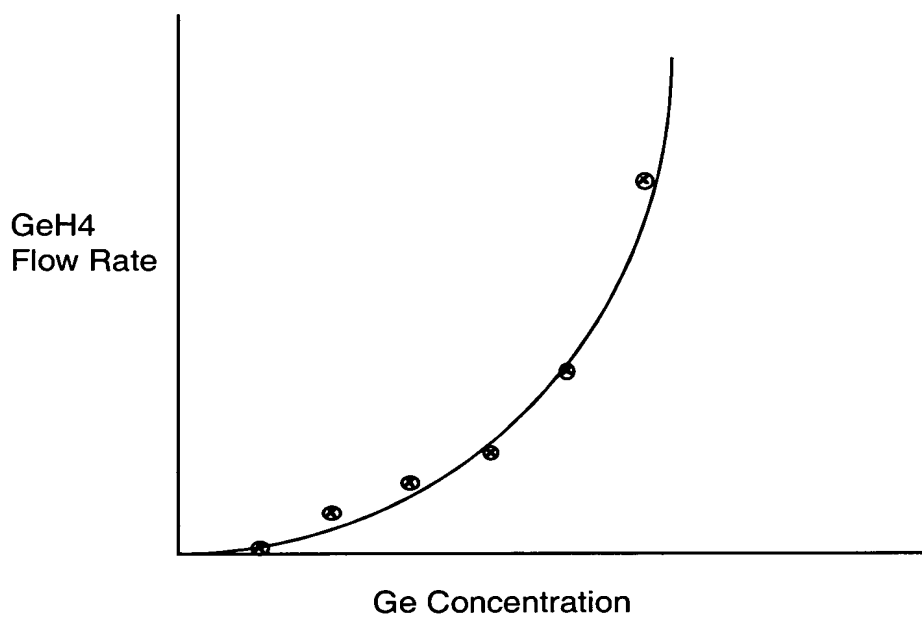
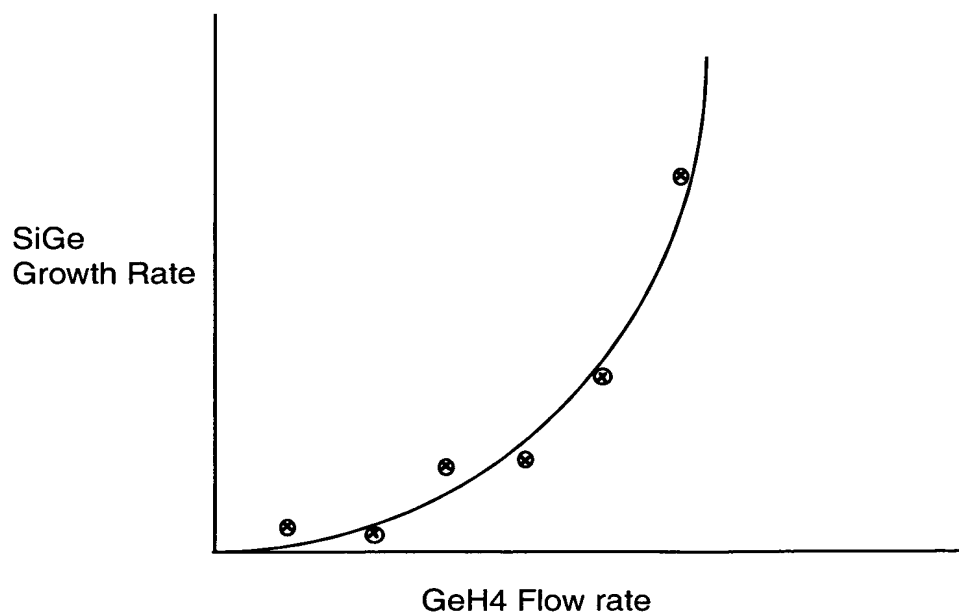


Figure 5

**Figure 6**

**Figure 7****Figure 8**

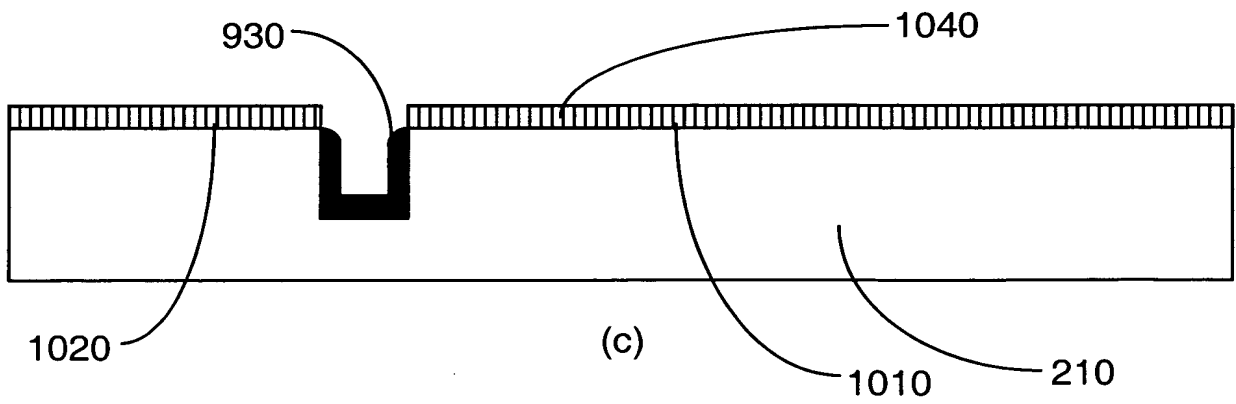
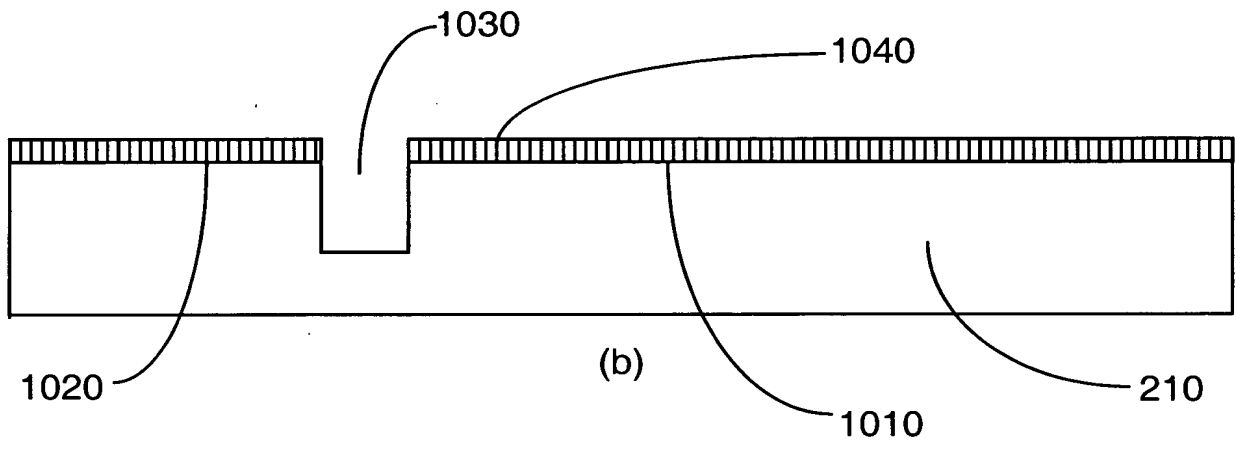
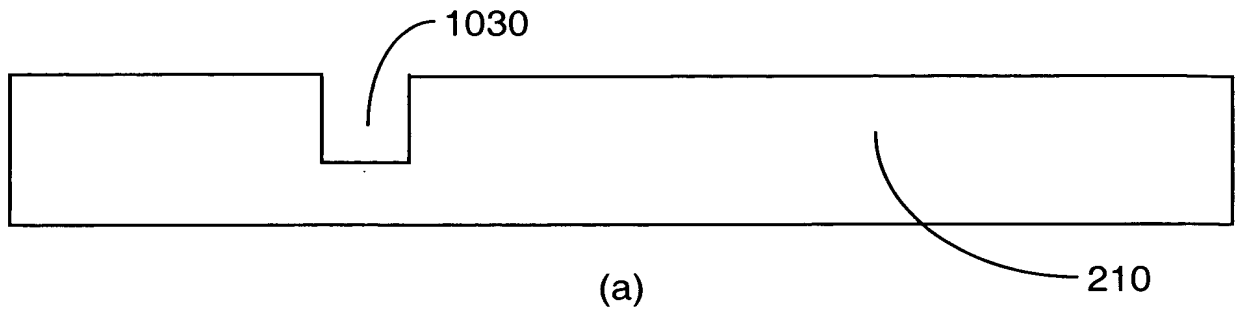


Figure 9

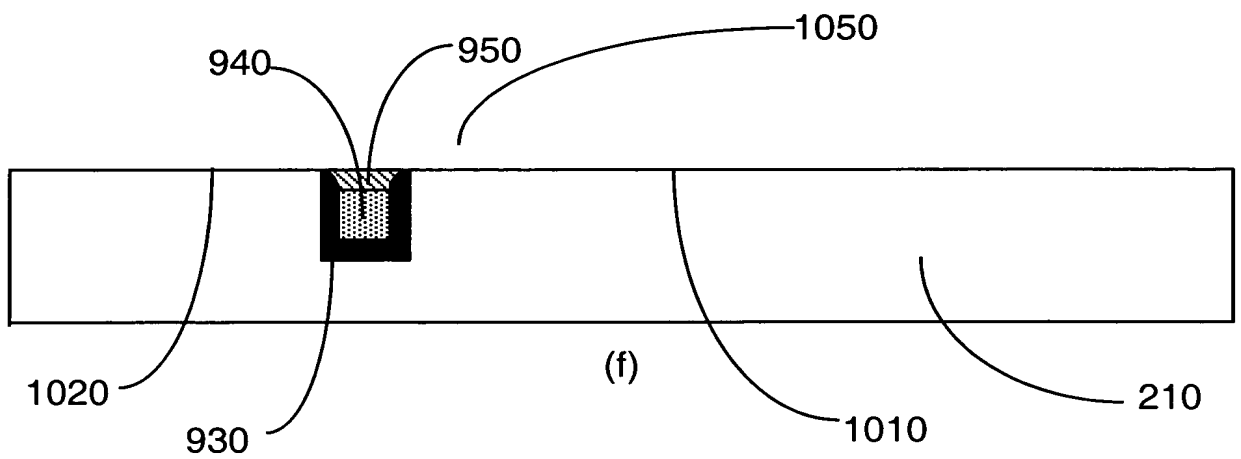
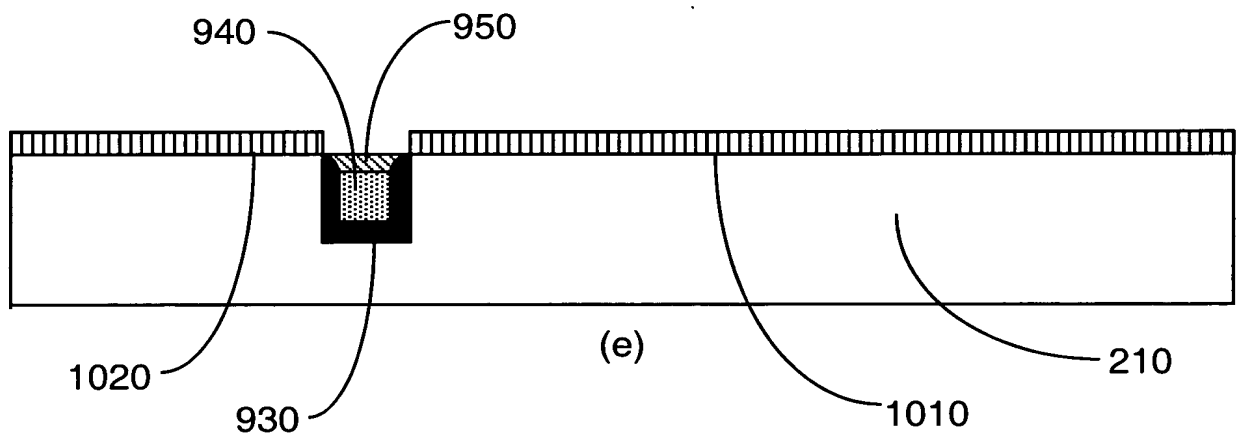
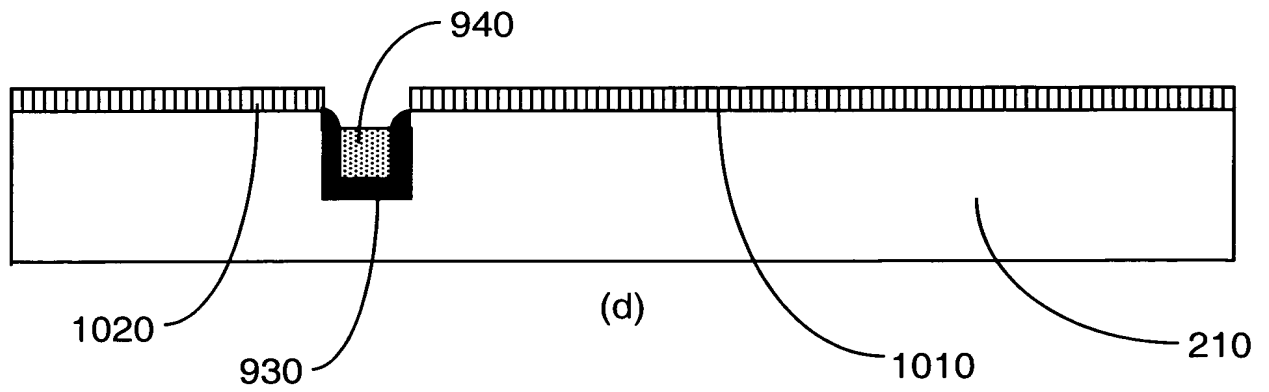
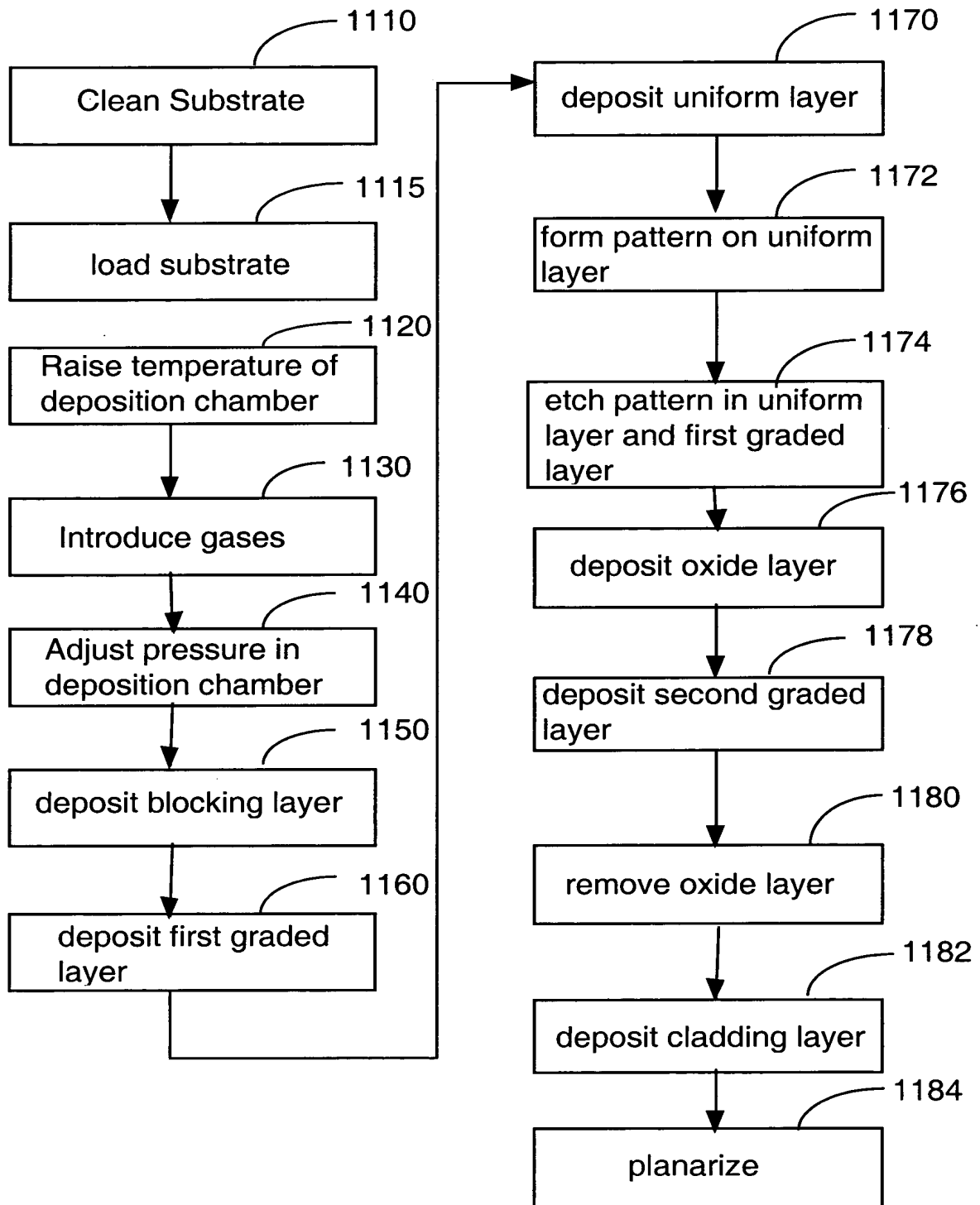


Figure 9

**Figure 10**

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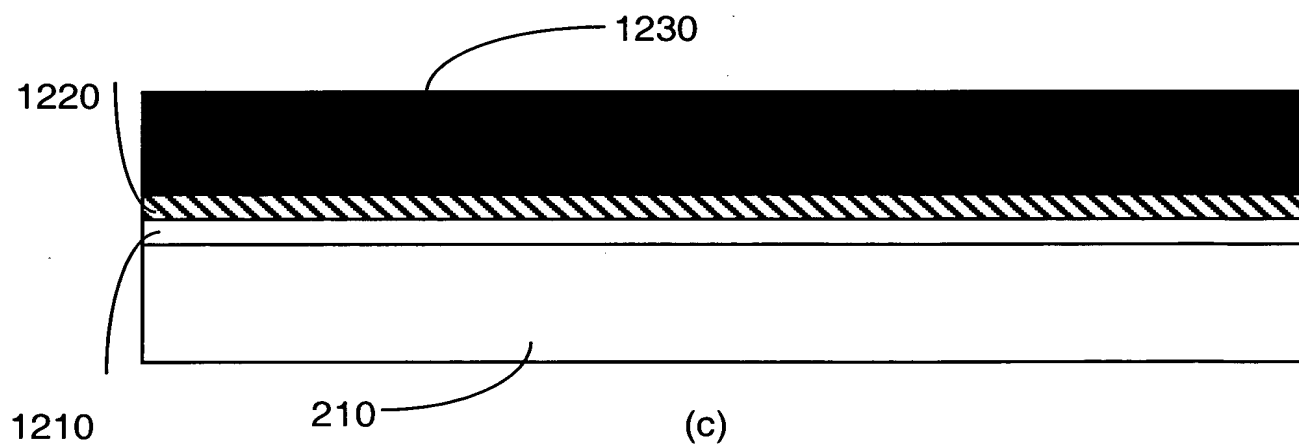
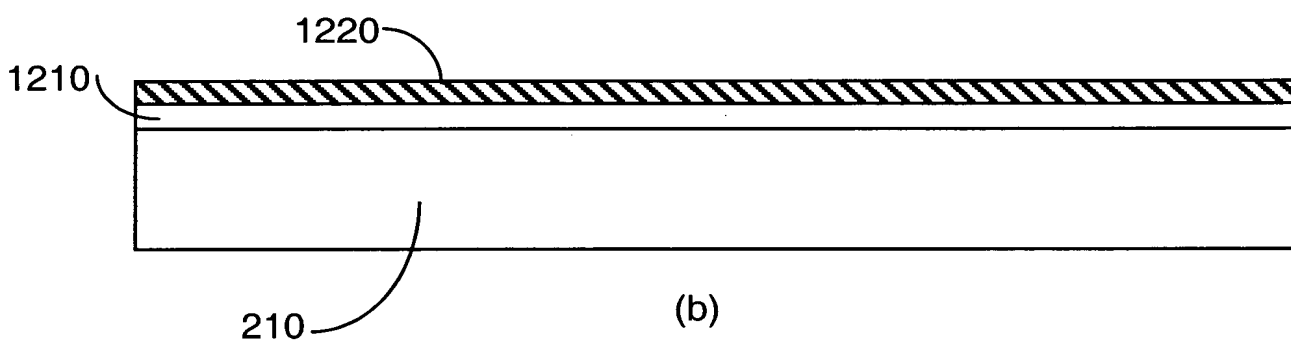
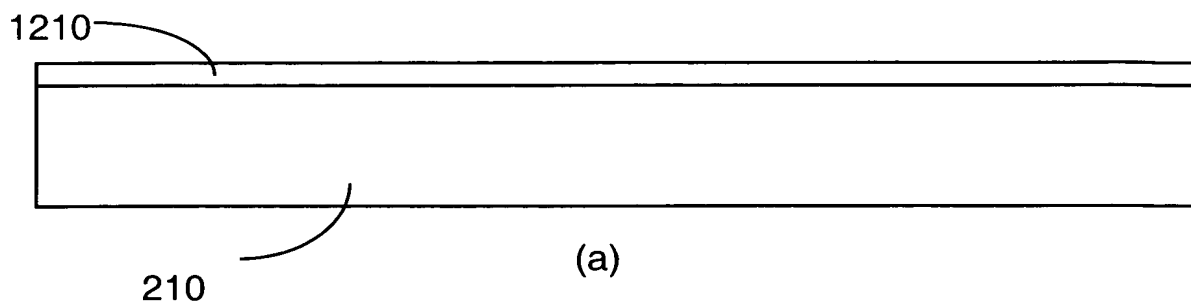


Figure 11

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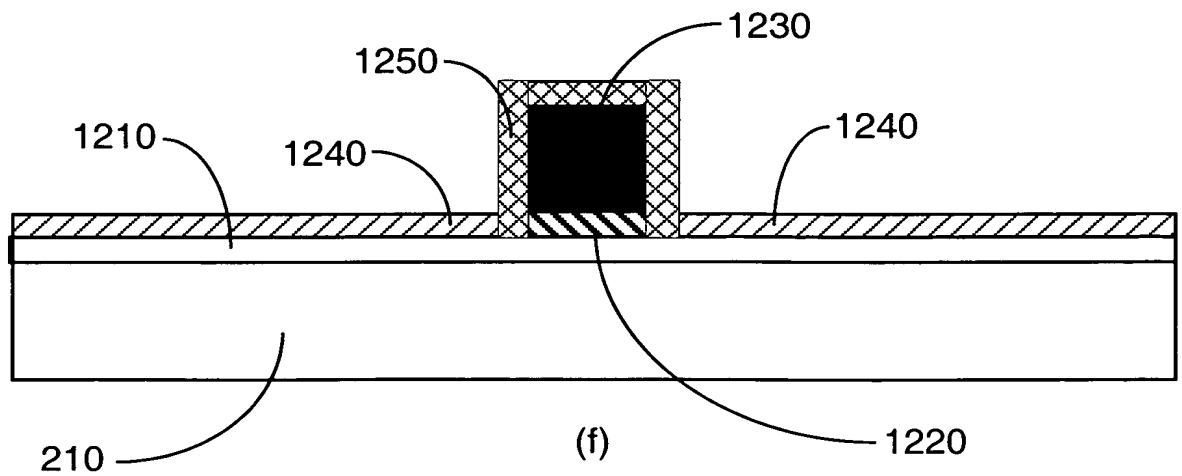
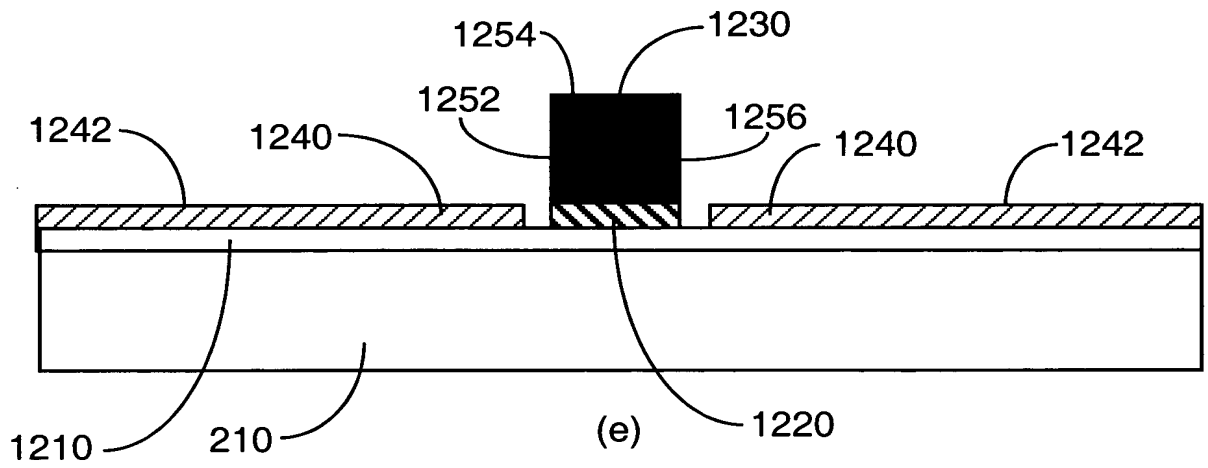
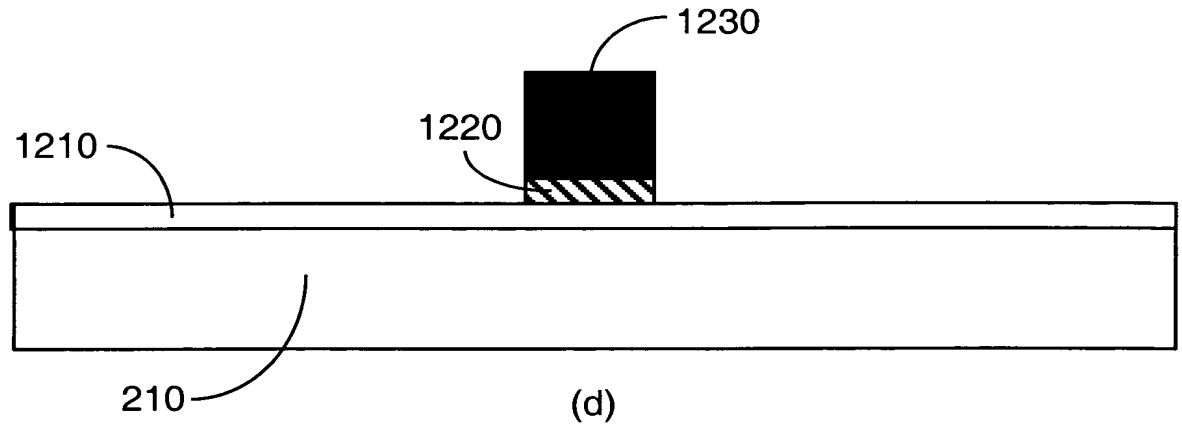


Figure 11

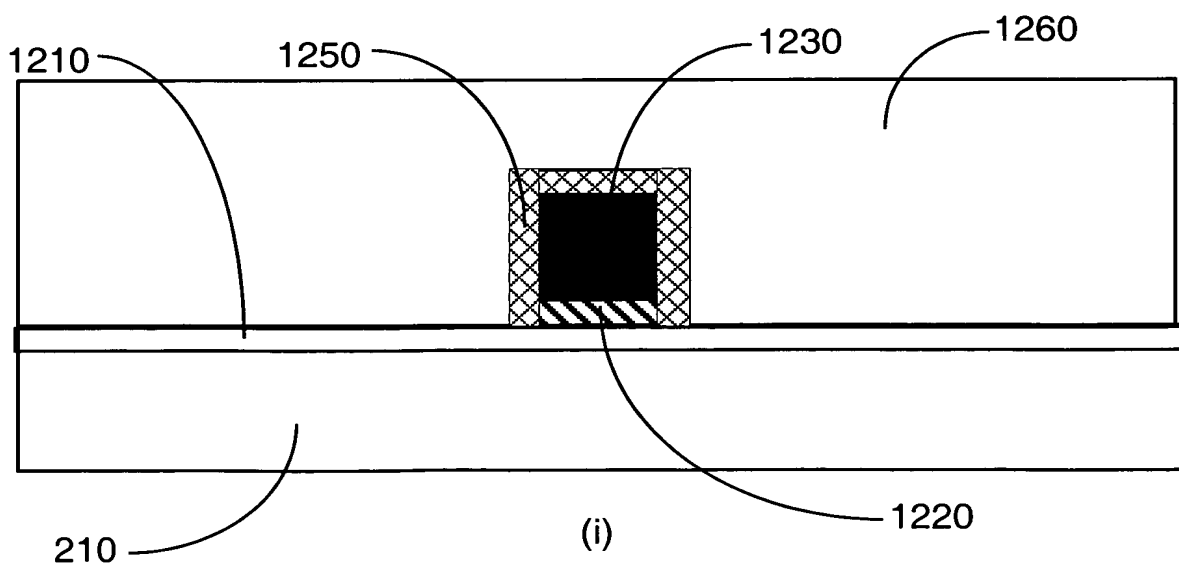
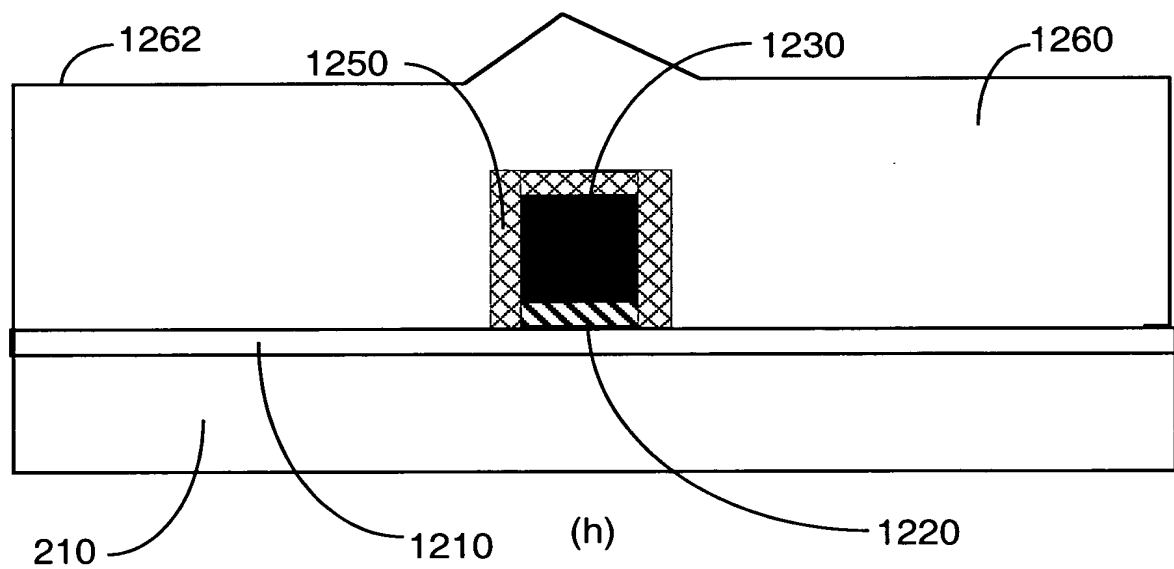
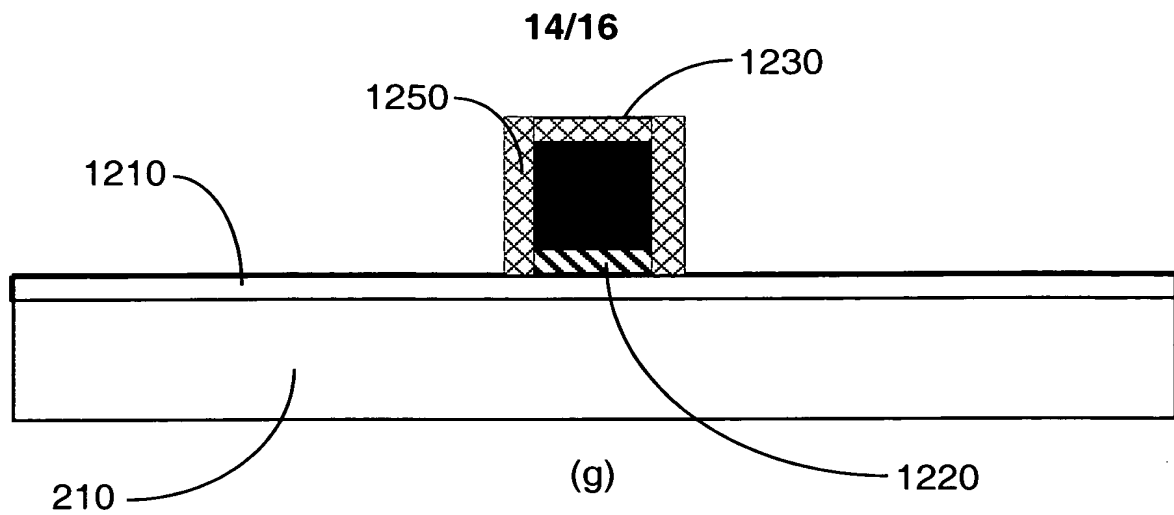


Figure 11

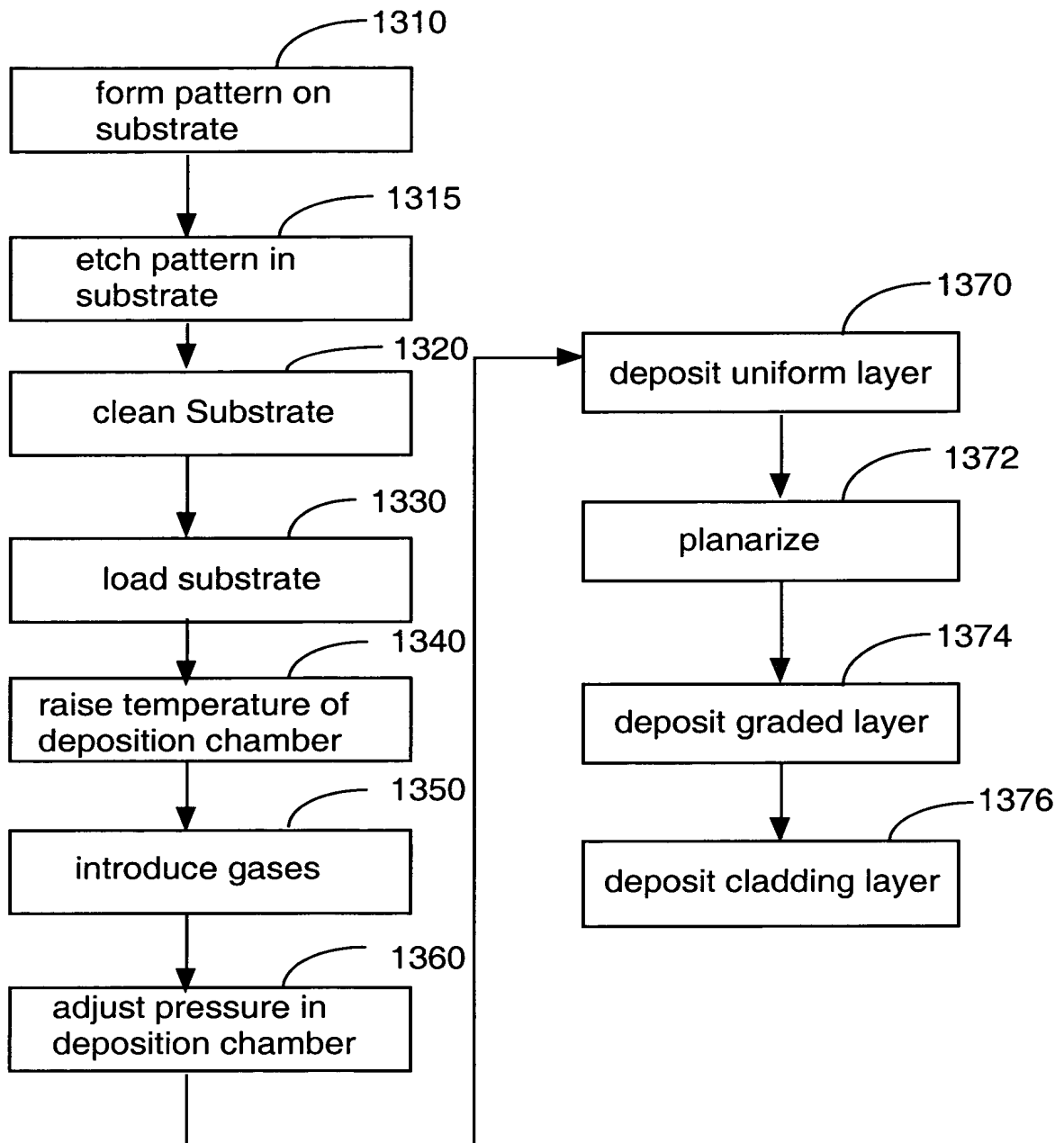


Figure 12

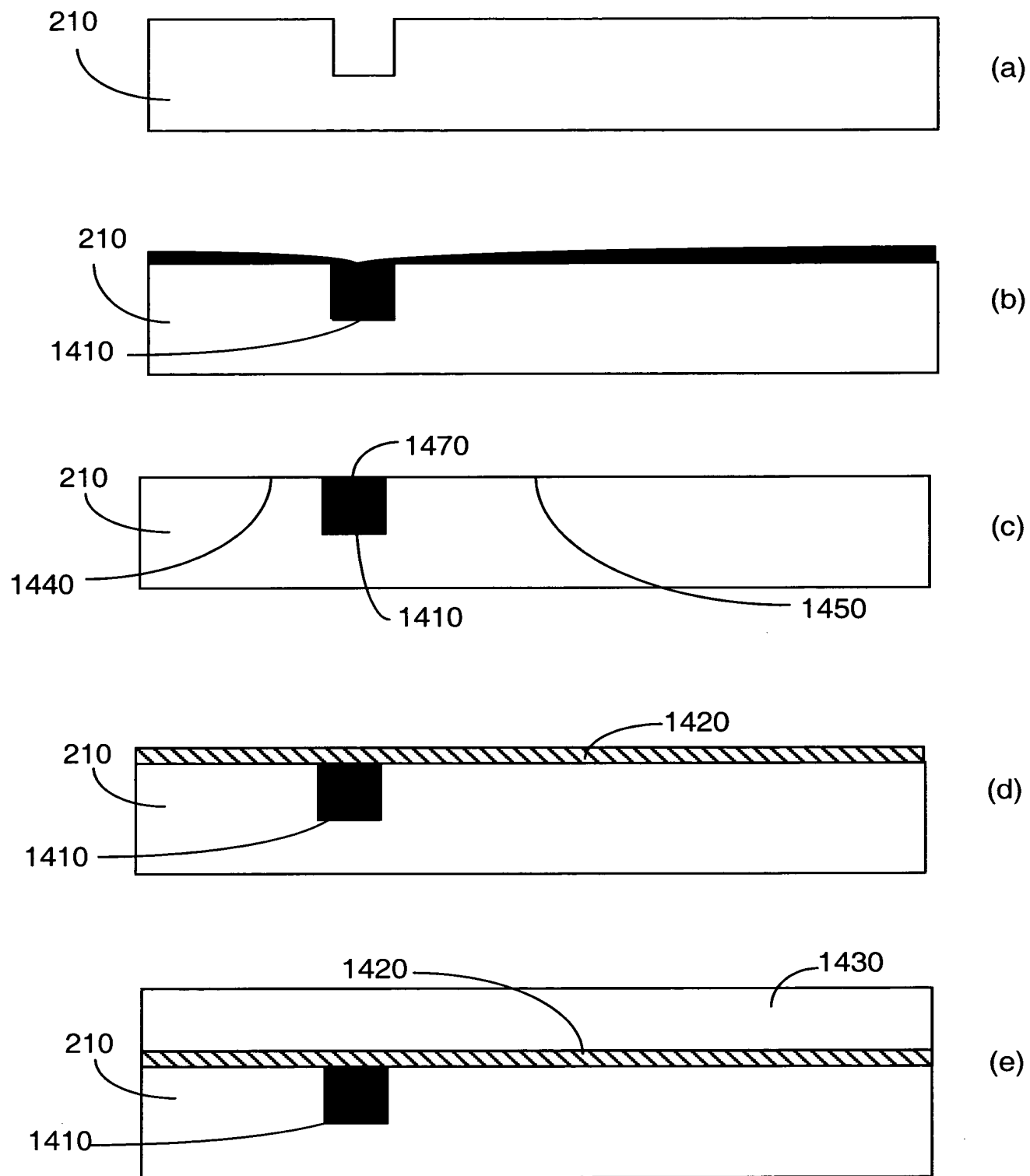


Figure 13